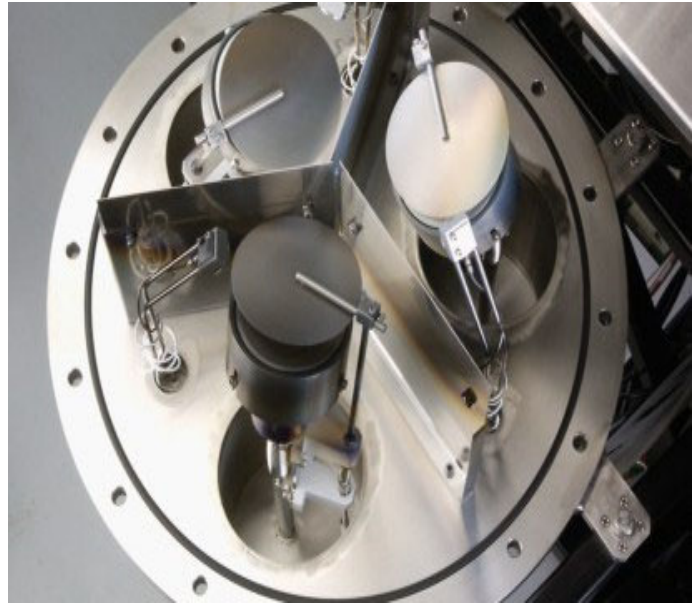


## Angstrom Nexdep RF/DC Sputtering System



In sputtering atoms are ejected from a solid target due to bombardment by energetic particles in plasma status. Deposits thin film of metals such as Al and Au and dielectrics such as ITO (Indium Tin oxide) and ZnO.

### Specifications

- Base pressure of  $<5 \times 10^{-7}$  Torr
- 16 W x 16 D x 20 " H aluminum high vacuum chamber
- Automated system control
- 3 sources
- Source to substrate distance of 150 mm
- 2 gases of Ar and O<sub>2</sub>
- Downstream single and mixed gas control system
- 2" circular sputter source
- 300 W RF supply system
- Rotating substrate system
- Backside Quartz lamp IR substrate heating